Vishay Siliconix

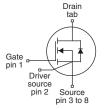
COMPLIANT

HALOGEN

FREE

E Series Power MOSFET





N-Channel MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 0.160			
Q _g max. (nC)	33			
Q _{gs} (nC)	7			
Q _{gd} (nC)	11			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

OF	RDERING INFORMATION	
Pac	ckage	PowerPAK 10 x 12
Lea	ad (Pb)-free and halogen-free	SiHK185N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	LIMIT	UNIT				
Drain-source voltage	V_{DS}	600	V				
Gate-source voltage	V_{GS}	± 30	V				
Continuous drain current (T _J = 150 °C)	V_{GS} at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	- I _D	19				
	$T_C = 100 ^{\circ}$ C		12	Α			
Pulsed drain current ^a	I _{DM}	44					
Linear derating factor			0.9	W/°C			
Single pulse avalanche energy b	E _{AS} 75		mJ				
Maximum power dissipation	P_{D}	114	W				
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C				
Drain-source voltage slope	T _J = 125 °C	dv/dt	V/ns				
Reverse diode dv/dt ^c		uv/ut	22	V/11S			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.3 A
- c. $I_{SD} \leq I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	50 ^a	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.1	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.63	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	5.0	V
Oak and the land		,	$V_{GS} = \pm 20 \text{ V}$ $V_{GS} = \pm 30 \text{ V}$		-	± 100	nA
Gate-source leakage	I _{GSS}	,			-	± 1	μA
7		V _{DS} =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	- 1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 9.5 A	-	0.160	0.185	Ω
Forward transconductance b	9 _{fs}	V _{DS} = 20 V, I _D = 9.5 A		-	5.3	-	S
Dynamic		•					
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	1085	-	pF
Output capacitance	C _{oss}	╗,	V _{DS} = 100 V,		56	_	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	5	-	
Effective output capacitance, energy related ^b	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	59	-	
Effective output capacitance, time related ^c	C _{o(tr)}			-	301	-	
Total gate charge	Qg			-	22	33	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 9.5 \text{ A}, V_{DS} = 480 \text{ V}$		7	-	nC
Gate-drain charge	Q_{gd}	1		-	11	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 9.5 A,		-	14	28	
Rise time	t _r			-	49	98	no
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		22	44	ns
Fall time	t _f			-	23	46	
Gate input resistance	R_g	f = 1 MHz		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	19	
Pulsed diode forward current	I _{SM}			-	-	44	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 9.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 9.5 A, di/dt = 100 A/ μ s, V _R = 25 V		-	282	564	ns
Reverse recovery charge	Q _{rr}			-	3.6	7.2	μC
Reverse recovery current	I _{RRM}			_	24	_	A

Notes

- a. When mounted on 1" x 1" FR4 board
- b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V
- c. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

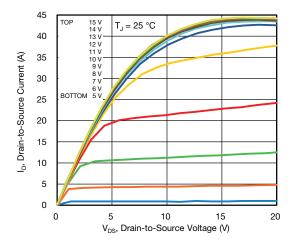


Fig. 1 - Typical Output Characteristics

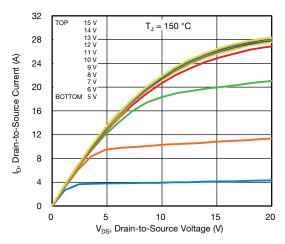


Fig. 2 - Typical Output Characteristics

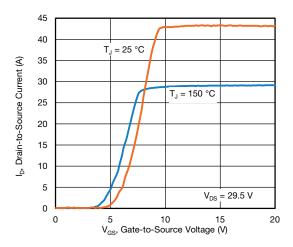


Fig. 3 - Typical Transfer Characteristics

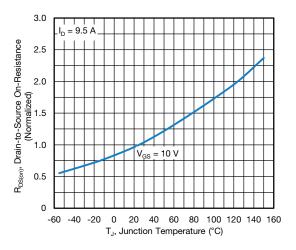


Fig. 4 - Normalized On-Resistance vs. Temperature

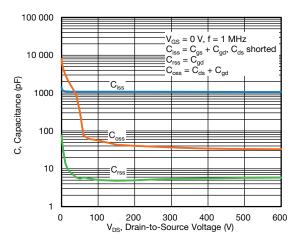


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

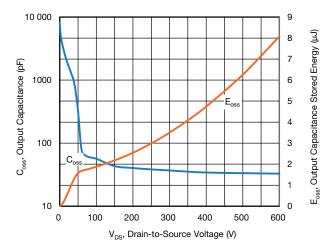


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



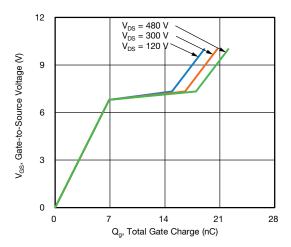


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

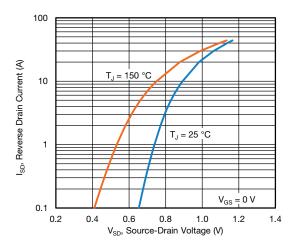


Fig. 8 - Typical Source-Drain Diode Forward Voltage

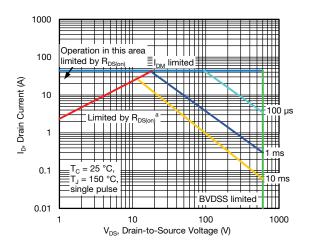


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

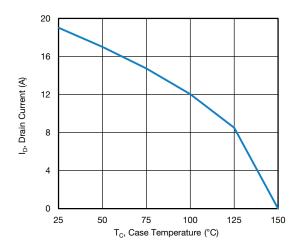


Fig. 10 - Maximum Drain Current vs. Case Temperature

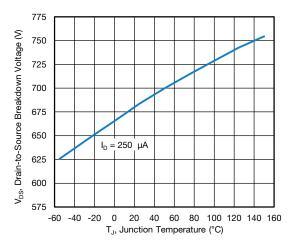


Fig. 11 - Temperature vs. Drain-to-Source Voltage



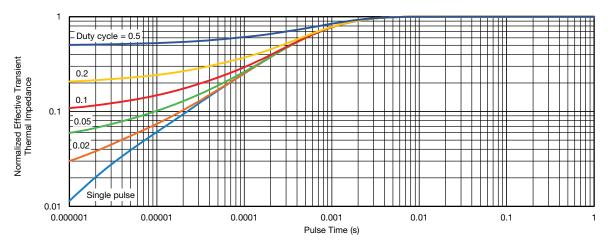


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

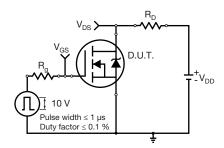


Fig. 13 - Switching Time Test Circuit

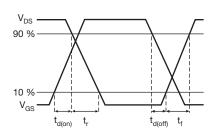


Fig. 14 - Switching Time Waveforms

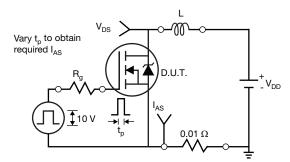


Fig. 15 - Unclamped Inductive Test Circuit

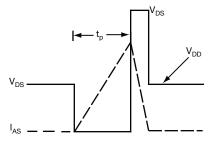


Fig. 16 - Unclamped Inductive Waveforms

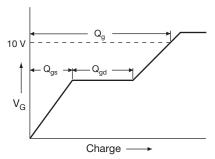


Fig. 17 - Basic Gate Charge Waveform

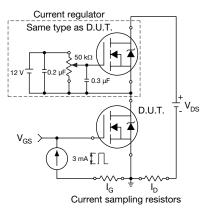
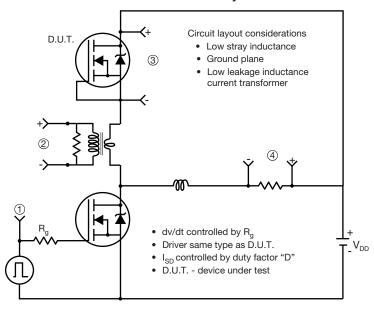


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



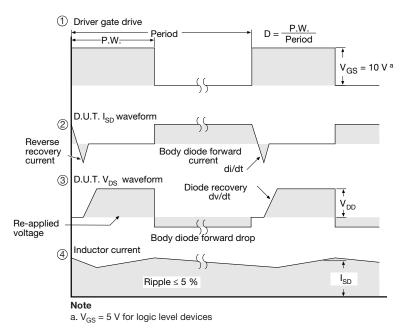
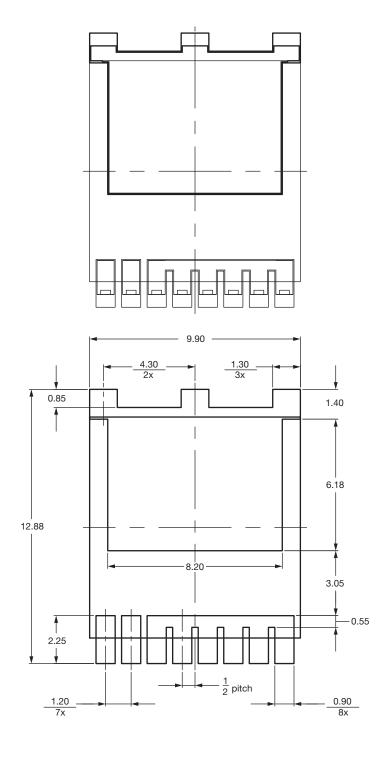


Fig. 19 - For N-Channel

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Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



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